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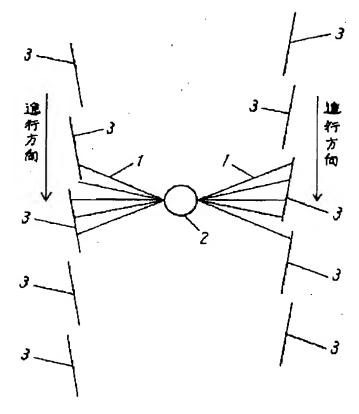
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TITLE

COATING FILM FORMATION AND

DEVICE THEREFOR



ABSTRACT :

PROBLEM TO BE SOLVED: To eliminate a variation in the thickness of a coating film formed on a base material to form the uniform coating film without lowering productivity with respect to a method of forming a coating film formed on a base material such as a printing circuit board used for various electronic equipments.

SOLUTION: Printing circuit boards 3 are conveyed along the advancing direction on both sides of a spray gun 2 with the head side thereof being inclined so that it is brought close to the spray gun 2 side. When the inclined printing circuit boards 3 approach the spray gun 2, a solder resist 1 is applied to form a coating film on the base materials. By replenishing the film thickness of the head part of the printed circuit boards 3 which is apt to become thin, a variation in the thickness of a film on the head part and the following part of the printing circuit boards 3 is eliminated to enable making uniform the film thickness on the head part and the following part of the base materials.

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